



## Product Change Notification / GBNG-26ZXKV002

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### Date:

28-Sep-2022

### Product Category:

Analog to Digital Converters, Digital Temperature Sensors, Linear Comparators, Linear Op Amps, Linear Programmable Gain Amplifiers, Linear Regulators, Power Management - System Supervisors/Voltage Detectors

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 5298 and 5298.001 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

### Affected CPNs:

[GBNG-26ZXKV002\\_Affected\\_CPN\\_09282022.pdf](#)  
[GBNG-26ZXKV002\\_Affected\\_CPN\\_09282022.csv](#)

### Notification Text:

**PCN Status:**Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.



**Method to Identify Change:**Traceability code

**Qualification Plan:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:**September 28, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_GBNG-26ZXKV002\\_Qual\\_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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GBNG-26ZXKV002 - CCB 5298 and 5298.001 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

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Affected Catalog Part Numbers (CPN)

TC1072-1.8VCH713  
TC1072-2.5VCH713  
TC1072-2.6VCH713  
TC1072-2.7VCH713  
TC1072-2.8VCH713  
TC1072-2.85VCH713  
TC1072-3.0VCH713  
TC1072-3.3VCH713  
TC1072-3.6VCH713  
TC1072-4.0VCH713  
TC1072-5.0VCH713  
TC1073-1.8VCH713  
TC1073-2.5VCH713  
TC1073-2.6VCH713  
TC1073-2.7VCH713  
TC1073-2.8VCH713  
TC1073-2.85VCH713  
TC1073-3.0VCH713  
TC1073-3.3VCH713  
TC1073-3.6VCH713  
TC1073-4.0VCH713  
TC1073-5.0VCH713  
MCP606T-I/OT  
MCP6271T-E/OT  
MCP6L71T-E/OT  
MCP6281T-E/OT  
MCP6291T-E/OT  
MCP1320T-46GE/OT  
MCP1320T-46KE/OT  
MCP1320T-46LE/OT  
MCP1320T-46FE/OT  
MCP1320T-25LE/OT  
MCP1320T-29BE/OT  
MCP1320T-29FE/OT  
MCP1320T-29LE/OT  
MCP1320T-29ME/OT  
MCP1320T-30BE/OT  
MCP1320T-30FE/OT  
MCP1320T-30LE/OT  
MCP1320T-19HI/OT  
MCP1320T-31KE/OT  
MCP1320T-31LE/OT  
MCP1320T-41LE/OT  
MCP1320T-42EE/OT  
MCP1320T-42JE/OT  
MCP1321T-46CE/OT

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MCP1321T-46GE/OT  
MCP1321T-46LE/OT  
MCP1321T-26GE/OT  
MCP1321T-29AE/OT  
MCP1321T-29CE/OT  
MCP1321T-29DE/OT  
MCP1321T-29FE/OT  
MCP1321T-29KE/OT  
MCP1321T-29LE/OT  
MCP1321T-29ME/OT  
MCP1321T-30LE/OT  
MCP1321T-31LE/OT  
MCP1322T-44LE/OT  
MCP1322T-46EE/OT  
MCP1322T-46LE/OT  
MCP1322T-29CE/OT  
MCP1322T-29LE/OT  
MCP1322T-31GE/OT  
MCP1322T-31LE/OT  
MCP1322T-32AE/OT  
MCP6021T-E/OT  
MCP6541UT-E/OT  
MCP6546UT-E/OT  
MCP601T-I/OT  
MCP601T-E/OT  
MCP6L1T-E/OT  
MCP3221A5T-I/OT  
MCP3221A5T-E/OT  
MCP3021A5T-E/OT  
MCP3221A2T-E/OT  
MCP3021A2T-E/OT  
MCP3221A3T-E/OT  
MCP3021A3T-E/OT  
MCP3221A4T-E/OT  
MCP3021A4T-E/OT  
MCP3221A0T-E/OT  
MCP3021A0T-E/OT  
MCP3221A6T-E/OT  
MCP3021A6T-E/OT  
MCP3221A7T-E/OT  
MCP3021A7T-E/OT  
MCP3221A1T-E/OT  
MCP3021A1T-E/OT  
MCP6001UT-I/OT  
MCP6001UT-E/OT  
MCP6L01UT-E/OT  
TC2014-1.8VCTTR  
TC2014-2.5VCTTR

TC2014-2.7VCTTR  
TC2014-2.8VCTTR  
TC2014-2.85VCTTR  
TC2014-3.0VCTTR  
TC2014-3.3VCTTR  
TC2014-5.0VCTTR  
TC2015-1.8VCTTR  
TC2015-2.5VCTTR  
TC2015-2.6VCTTR  
TC2015-2.7VCTTR  
TC2015-2.8VCTTR  
TC2015-2.85VCTTR  
TC2015-3.0VCTTR  
TC2015-3.3VCTTR  
TC2015-5.0VCTTR  
TC2054-1.8VCTTR  
TC2054-2.5VCTTR  
TC2054-2.6VCTTR  
TC2054-2.7VCTTR  
TC2054-2.8VCTTR  
TC2054-2.85VCTTR  
TC2054-3.0VCTTR  
TC2054-3.3VCTTR  
TC2054-5.0VCTTR  
TC2055-1.8VCTTR  
TC2055-2.5VCTTR  
TC2055-2.6VCTTR  
TC2055-2.7VCTTR  
TC2055-2.8VCTTR  
TC2055-2.85VCTTR  
TC2055-3.0VCTTR  
TC2055-3.3VCTTR  
TC2055-5.0VCTTR  
TC2185-1.8VCTTR  
TC2185-2.5VCTTR  
TC2185-2.6VCTTR  
TC2185-2.7VCTTR  
TC2185-2.8VCTTR  
TC2185-2.85VCTTR  
TC2185-3.0VCTTR  
TC2185-3.3VCTTR  
TC2185-5.0VCTTR  
TC2186-1.8VCTTR  
TC2186-2.5VCTTR  
TC2186-2.6VCTTR  
TC2186-2.7VCTTR  
TC2186-2.8VCTTR  
TC2186-2.85VCTTR

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TC2186-3.3VCTTR  
TC2186-5.0VCTTR  
MCP6231T-E/OT  
MCP6231UT-E/OT  
MCP6241T-E/OT  
MCP6241UT-E/OT  
MCP6G01T-E/OT  
MCP6G01UT-E/OT  
MCP6041T-I/OT  
MCP6041T-E/OT  
MCP6141T-E/OT  
MCP6286T-E/OT  
MCP6401T-E/OT  
MCP6401UT-E/OT  
MCP6441T-E/OT  
MCP6L91T-E/OT-HCM  
MCP6L91T-E/OT  
MCP1316T-20LI/OT  
MCP1316T-23LI/OT  
MCP1316T-24MI/OT  
MCP1316MT-20LI/OT  
MCP1316MT-20RI/OT  
MCP1316MT-23LI/OT  
MCP1319T-31QI/OT  
MCP1319MT-24QI/OT  
MCP1321T-20LI/OT  
MCP1321T-20QI/OT  
MCP1321T-43BE/OT  
MCP1316MT-29JE/OT  
MCP1316T-44JE/OT  
MCP1316T-44LE/OT  
MCP1316T-44NE/OT  
MCP1316T-46BE/OT  
MCP1316T-46CE/OT  
MCP1316T-46FE/OT  
MCP1316T-46KE/OT  
MCP1316T-46LE/OT  
MCP1316T-47FE/OT  
MCP1316T-25LE/OT  
MCP1316T-26JE/OT  
MCP1316T-26LE/OT  
MCP1316T-27LE/OT  
MCP1316T-29AE/OT  
MCP1316T-29EE/OT  
MCP1316T-29FE/OT  
MCP1316T-29LE/OT  
MCP1316T-29NE/OT  
MCP1316T-30CE/OT

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MCP1316T-31LE/OT  
MCP1316T-31RE/OT  
MCP1316T-32LE/OT  
MCP1316MT-45GE/OT  
MCP1316MT-46FE/OT  
MCP1316MT-46GE/OT  
MCP1316MT-46LE/OT  
MCP1316MT-26CE/OT  
MCP1316MT-29GE/OT  
MCP1316MT-29KE/OT  
MCP1316MT-29LE/OT  
MCP1316MT-29ME/OT  
MCP1316MT-30HE/OT  
MCP1316MT-31LE/OT  
MCP1316MT-33LE/OT  
MCP1317T-46LE/OT  
MCP1317T-25LE/OT  
MCP1317T-29LE/OT  
MCP1317T-31AE/OT  
MCP1317T-31LE/OT  
MCP1317T-31RE/OT  
MCP1317T-33LE/OT  
MCP1318T-45LE/OT  
MCP1318T-46LE/OT  
MCP1318T-46ME/OT  
MCP1318T-29EE/OT  
MCP1318T-29HE/OT  
MCP1318T-29LE/OT  
MCP1318MT-46BE/OT  
MCP1318MT-46LE/OT  
MCP1318MT-29BE/OT  
MCP1318MT-29EE/OT  
MCP1318MT-29LE/OT  
MCP1319T-44LE/OT  
MCP1319T-46LE/OT  
MCP1319T-47QE/OT  
MCP1319T-28LE/OT  
MCP1319T-29CE/OT  
MCP1319T-29LE/OT  
MCP1319T-42LE/OT  
MCP1319MT-46LE/OT  
MCP1319MT-47QE/OT  
MCP1319MT-26AE/OT  
MCP1319MT-26EE/OT  
MCP1319MT-28LE/OT  
MCP1319MT-29LE/OT  
MCP1319MT-30GE/OT  
MCP1319MT-33AE/OT



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MCP1320T-27ME/OT  
MCP1320T-29GE/OT  
MCP1320T-29RE/OT  
MCP1322T-27LE/OT  
MCP6401T-H/OT  
MCP6406T-H/OT  
TC1189QECTTR  
TC1189RECTTR  
TC1189SECTTR  
TC1189TECTTR  
TC1189TECTTRBAA  
TC1188QECTTR  
TC1188RECTTR  
TC1188SECTTR  
TC1188TECTTR  
TC1185-2.95VCT713  
TC1014-1.8VCT713  
TC1014-2.5VCT713  
TC1014-2.6VCT713  
TC1014-2.7VCT713  
TC1014-2.8VCT713  
TC1014-2.85VCT713  
TC1014-3.0VCT713  
TC1014-3.1VCT713  
TC1014-3.3VCT713  
TC1014-3.6VCT713  
TC1014-4.0VCT713  
TC1014-5.0VCT713  
TC1015-1.8VCT713  
TC1015-2.5VCT713  
TC1015-2.6VCT713  
TC1015-2.7VCT713  
TC1015-2.8VCT713  
TC1015-2.85VCT713  
TC1015-3.0VCT713  
TC1015-3.3VCT713  
TC1015-3.6VCT713  
TC1015-4.0VCT713  
TC1015-5.0VCT713  
TC1015-2.8VCT713BAB  
TC1015-3.3VCT713BAC  
TC1015-2.6VCT713BAE  
TC1015-2.85VCT713BAF  
TC1054-1.8VCT713  
TC1054-2.5VCT713  
TC1054-2.6VCT713  
TC1054-2.7VCT713  
TC1054-2.8VCT713

TC1054-3.0VCT713  
TC1054-3.3VCT713  
TC1054-3.6VCT713  
TC1054-4.0VCT713  
TC1054-4.2VCT713  
TC1054-5.0VCT713  
TC1055-1.8VCT713  
TC1055-2.5VCT713  
TC1055-2.6VCT713  
TC1055-2.7VCT713  
TC1055-2.8VCT713  
TC1055-2.85VCT713  
TC1055-3.0VCT713  
TC1055-3.3VCT713  
TC1055-3.6VCT713  
TC1055-4.0VCT713  
TC1055-5.0VCT713  
TC1185-1.8VCT713  
TC1185-2.0VCT713  
TC1185-2.5VCT713  
TC1185-2.6VCT713  
TC1185-2.7VCT713  
TC1185-2.8VCT713  
TC1185-2.85VCT713  
TC1185-3.0VCT713  
TC1185-3.3VCT713  
TC1185-3.6VCT713  
TC1185-4.0VCT713  
TC1185-4.15VCT713  
TC1185-5.0VCT713  
TC1186-1.8VCT713  
TC1186-2.5VCT713  
TC1186-2.6VCT713  
TC1186-2.7VCT713  
TC1186-2.8VCT713  
TC1186-2.85VCT713  
TC1186-3.0VCT713  
TC1186-3.3VCT713  
TC1186-3.6VCT713  
TC1186-4.0VCT713  
TC1186-5.0VCT713  
TC1224-1.8VCTTR  
TC1224-2.5VCTTR  
TC1224-2.6VCTTR  
TC1224-2.7VCTTR  
TC1224-2.8VCTTR  
TC1224-2.85VCTTR  
TC1224-3.0VCTTR

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GBNG-26ZXKV002 - CCB 5298 and 5298.001 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC10xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 6L and 5L SOT-23 packages assembled at MMT assembly site.

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TC1224-3.6VCTTR  
TC1224-4.0VCTTR  
TC1224-5.0VCTTR  
TC1223-1.8VCTTR  
TC1223-2.5VCTTR  
TC1223-2.6VCTTR  
TC1223-2.7VCTTR  
TC1223-2.8VCTTR  
TC1223-2.85VCTTR  
TC1223-3.0VCTTR  
TC1223-3.3VCTTR  
TC1223-3.6VCTTR  
TC1223-4.0VCTTR  
TC1223-4.2VCTTR  
TC1223-5.0VCTTR  
TC1070VCT713  
TC1071VCT713  
TC1187VCT713  
TC1187VCT713AAA  
TC1187VCTMR  
TC1016-1.8VCTTR  
TC1016-1.85VCTTR  
TC1017-2.0VCTTR  
TC1016-2.6VCTTR  
TC1016-2.7VCTTR  
TC1016-2.8VCTTR  
TC1016-2.85VCTTR  
TC1016-2.9VCTTR  
TC1016-3.0VCTTR  
TC1016-3.3VCTTR  
TC1016-4.0VCTTR  
TC1017-1.8VCTTR  
TC1017-1.9VCTTR  
TC1017-2.5VCTTR  
TC1017-2.6VCTTR  
TC1017-2.7VCTTR  
TC1017-2.8VCTTR  
TC1017-2.9VCTTR  
TC1017-3.0VCTTR  
TC1017-3.3VCTTR  
TC1017-4.0VCTTR  
TC1017-1.85VCTTR  
TC1017-2.85VCTTR  
MCP6561T-E/OT  
MCP6561UT-E/OT  
MCP6566T-E/OT  
TC74A0-3.3VCTTR  
TC74A0-5.0VCTTR

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TC74A1-5.0VCTTR

TC74A2-3.3VCTTR

TC74A2-5.0VCTTR

TC74A3-3.3VCTTR

TC74A3-5.0VCTTR

TC74A4-3.3VCTTR

TC74A4-5.0VCTTR

TC74A5-3.3VCTTR

TC74A5-5.0VCTTR

TC74A6-3.3VCTTR

TC74A6-5.0VCTTR

TC74A7-3.3VCTTR

TC74A7-5.0VCTTR

MCP1824T-0802E/OT

MCP1824T-1202E/OT

MCP1824T-1802E/OT

MCP1824T-2502E/OT

MCP1824T-3002E/OT

MCP1824T-3302E/OT

MCP1824T-5002E/OT

MCP1824T-ADJE/OTAAA

MCP1824T-ADJE/OT



**MICROCHIP**

## **QUALIFICATION PLAN SUMMARY**

**PCN #: GBNG-26ZXKV002**

**Date:  
September 15, 2022**

**Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected TC10xx device family available in 6L SOT-23 package assembled at MMT assembly site. The selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 5L SOT-23 package assembled at MMT assembly site will qualify by similarity (QBS).**

**Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected TC10xx device family available in 6L SOT-23 package assembled at MMT assembly site. The selected MCP13xx, MCP1824, MCP3021Axx, MCP3221Axx, MCP6xx, TC118xx, TC122xx, TC20xx, TC218xx and TC74Axx device families available in 5L SOT-23 package assembled at MMT assembly site will qualify by similarity (QBS).**

<b><u>Misc.</u></b>	Assembly site	MMT
	BD Number	BD-000741/01
	MP Code (MPC)	GBAH1YC8XF33
	Part Number (CPN)	TC1073-3.3VCH713
	MSL information	MSL-1@260C
	Assembly Shipping Media (T/R, Tube/Tray)	TnR
	Base Quantity Multiple (BQM)	3000
	CCB No.	5298 and 5298.001
<b><u>Lead-Frame</u></b>	Paddle size	72x41 mils
	Material	CDA194
	DAP Surface Prep	Ag Spot Plated
	Treatment	No
	Process	Stamped
	Lead-lock	No
	Part Number	10100602
	Lead Plating	Matte Tin
	Strip Size	228.288x50.800mm
	Strip Density	192units/strip
<b><u>Bond Wire</u></b>	Material	CuPdAu
<b><u>Die Attach</u></b>	Part Number	8900NC
	Conductive	No
<b><u>MC</u></b>	Part Number	G600V
<b><u>PKG</u></b>	PKG Type	SOT-23
	Pin/Ball Count	6

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	3	15	0 fails after TC	5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	3	15		5	MMT/MTAI	30 bonds from a minimum of 5 devices.
Wire Sweep		5	0	3	15	0		MMT	Required for any reduction in wire bond thickness.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	MMT/ MTAI	
HTSL (High Temp Storage Life)	JESD22-A103. +175 C for 504 hours. Electrical test pre and post stress at +25°C and hot temp	45	5	3	150	0	25	MTAI	"Must be in progress at time of package release to production, but completion is not required for release to production.  3 lots are required for Cu wire qual.  Post-stress Electrical Test Window Time: Within 168 hours. Refer to JESD22-A103 for details.
Preconditioning - Required for surface mount devices	JESD22-A113. +150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020E for package type; Electrical test pre and post stress at +25°C.  MSL-1/260C	231	15	3	738	0	15	MTAI	Spares should be properly identified. 77 parts from each lot to be used for HAST, uHAST, Temp Cycle test.

Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Test Site	Special Instructions
HAST	JESD22-A110. +130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp.	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.  Post-stress Electrical Test Window Time: Within 48 hours. Note: For intermediate readouts, devices shall be returned to stress within 96 hours of the end of ramp down. (can be extended to 144 hours, and the time to return to stress to as much as 288 hours by placing the devices in sealed moisture barrier bags without desiccant). Refer to JESD22-A110 for details
Unbiased HAST	JESD22-A118 +130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.  Post-stress Electrical Test Window Time: Within 48 hours. Note: for intermediate readouts, devices shall be returned to stress within 96 hours of the end of ramp down. (can be extended to 144 hours, and the time to return to stress to as much as 288 hours by placing the devices in sealed moisture barrier bags, the bags should be non-vacuum sealed without a N2 purge and without desiccant). Refer to JESD22-A118 for details.
Temp Cycle	JESD22-A104. -65°C to +150°C for 500 cycles.  Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, test following Temp Cycle stress	77	5	3	246	0	15	MTAI	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.